ANSYS Delivers New Solutions For Reliable And Efficient Automotive, Mobile And HPC Electronic Designs

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PITTSBURGH, June 6, 2017 /PRNewswire/ -- ANSYS (NASDAQ: ANSS) is expanding its best-in-class engineering simulation architecture to combine the advanced computer science of elastic computing, big data and machine learning to the physics-based world of engineering simulation. Available today, ANSYS® RedHawk-SC™, ANSYS® Path-FX™ and ANSYS® CMA™ enable automotive, mobile and high-performance computing (HPC) organizations to accelerate electronic product innovation and improve performance, reliability and cost.

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Today's leading automotive, HPC and mobile electronics require semiconductor chips with advanced process nodes to improve processor power consumption. As the scale and complexity of these chips increase, emerging design technologies need to provide optimized tools to quickly and accurately analyze and manage data. RedHawk-SC, Path-FX and CMA empower organizations to meet the growing electronic system demands for advanced driver-assistance systems, mobile phones, GPU-powered artificial intelligence and data center networking.

RedHawk-SC brings unprecedented performance and scalability to the production proven ANSYS® RedHawk™ platform. RedHawk-SC's elastic compute engine gives users a 10x improvement in capacity and scalability architecture over previous releases of RedHawk. Elastic compute enables customers to efficiently leverage commodity computers in private or public cloud environments, without requiring expensive, dedicated high memory computers.

With the addition of ANSYS® SeaScape™ technologies, RedHawk users now have access to big data analytics, and popular machine learning packages, that reduce power while increasing performance and reliability of semiconductor designs. Customers can process large amounts of data from different physics-based simulations and chip design data to drive optimizations that improve the cost, performance and reliability of designs.

ANSYS Path-FX supports users with on-chip variability analyses that are essential to advanced process node designs, where power, timing and parametric yield are critical. Path-FX integrates with RedHawk-SC to provide comprehensive timing and voltage variability analysis, complementing timing sign-off tools from third-party vendors. ANSYS CMA provides a direct link for electronic system designers to accurately model and analyze power integrity and signal integrity effects efficiently through sophisticated chip power models produced by RedHawk-SC.

"Our focus on multiphysics simulation for chip-package-system delivers unique and significant customer value to a large and growing number of the top semiconductor and electronics companies," said John Lee, general manager, ANSYS. "We are excited to be at the forefront of applying advanced computational sciences such as machine learning and big data to drive results that enable our automotive, mobile and HPC electronic system customers to realize their product promise."

The new products will be highlighted at the Design Automation Conference, June 18-22 in Austin, Texas, and at the ANSYS Executive Seminars in Silicon Valley and Austin in June. The seminars are open to key customers, and industry analysts, and will focus on machine learning, advanced semiconductor and automotive reliability flows.

About ANSYS, Inc.

If you've ever seen a rocket launch, flown on an airplane, driven a car, used a computer, touched a mobile device, crossed a bridge, or put on wearable technology, chances are you've used a product where ANSYS software played a critical role in its creation. ANSYS is the global leader in engineering simulation. We help the world's most innovative companies deliver radically better products to their customers. By offering the best and broadest portfolio of engineering simulation software, we help them solve the most complex design challenges and create products limited only by imagination. Founded in 1970, ANSYS employs thousands of professionals, many of whom are expert M.S. and Ph.D.-level engineers in finite element analysis, computational fluid dynamics, electronics, semiconductors, embedded software and design optimization. Headquartered south of Pittsburgh, Pennsylvania, U.S.A., ANSYS has more than 75 strategic sales locations throughout the world with a network of channel partners in 40+ countries. Visit www.ansys.com for more information.

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